

e-Manufacturing & Design Collaboration Symposium 2014						
Afternoon		Session — Engineering Excellence	Venue	Ballroom C 10/F		
Time	Duration	Topic	Speaker	Association	Chair	
13:30	00:20	Simulation-Based Wip Management Versus Scheduling For Semiconductor Manufacturing – A Comparison	Peter Lendermann	D-SIMLAB	Dr. Chris Luoh	
13:50	00:20	On the Dynamics of Topological Patterns in Statistical Imputation	K. Hui	tsmc		
14:10	00:20	Do We Still Need Daily Production Target Setting in Fully Automated Fabs	Yu-Ting Kao	NTU		
14:30	00:20	Advanced Process Control of Effective Field Height in a Single Wafer Spin Cleaning Tool	Wen-Ming Chang	Macronix		
14:50	00:20	3D Interconnect Simulation Applied to CMP Thickness Variations	Shi-Hao Huang	Synopsis		
15:10	00:30	Break				
15:40	00:20	The technology about coordination of the production process associated with complex product based on Task-Kitting-Crafts	Xue Zhen	BIT	Dr. Chris Luoh	
16:00	00:20	FOUP Mini-Environment Contaminants Analysis in Semiconductor Manufacturing	YiTing Kuo	Macronix		
16:20	00:20	Sensitivity Integrity for tool monitoring	Po Feng Tsai	tsmc		
16:40	00:20	Tiny Physical Defects Inspection by Optimized EBI Methodology	Liao Hsiang-Chou	Macronix		
17:00		Adjourn				

Final programme is subject to change without prior notice.